# PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
STMICROELECTRONICS ASIA PACIFIC PTE LTD.	10/04/2011

## **RECEIVING PARTY DATA**

Name:	STMicroelectronics PTE LTD.
Street Address:	28 Ang Mo Kio Industrial Park 2
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569508

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12651295

#### **CORRESPONDENCE DATA**

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via US Mail.

Correspondent Name: Hayley J. Stevens
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Address Line 4: Seattle, WASHINGTON 98104

ATTORNEY DOCKET NUMBER: 851663.501

NAME OF SUBMITTER: Hayley J. Stevens

Total Attachments: 2

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PATENT REEL: 027110 FRAME: 0533 H \$40.00 12651;

#### ASSIGNMENT

WHEREAS, Assignor STMICROELECTRONICS ASIA PACIFIC PTE LTD., (hereinafter "Assignor") a Singapore corporation, was assigned certain rights in and to certain inventions, and application for Letters Patent of the United States entitled "FAN-OUT WAFER LEVEL PACKAGE WITH POLYMERIC LAYER FOR HIGH RELIABILITY," filed on December 31, 2009 as U.S. Application No. 12/651,295; and

WHEREAS, STMICROELECTRONICS PTE LTD., a Singapore corporation, residing or having a principal place of business at 28 Ang Mo Kio Industrial Park 2, Singapore 569508 (hereinafter "Assignee"), is desirous of acquiring the entire right, title and interest in and to the inventions and the application for Letters Patent of the United States, and in and to any Letters Patent to be obtained therefor and thereon worldwide;

NOW, THEREFORE, for good and sufficient consideration, the receipt of which is acknowledged, to the extent Assignor had, or has any right, title, or interest in and to the inventions and application for Letters Patent, Assignor has sold, assigned, transferred and set over, and does sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, all right, title and interest in and to the above-mentioned inventions and application for Letters Patent that Assignor owns, and in and to any and all direct and indirect divisions, continuations and continuations-in-part of the application, and any and all Letters Patent in the United States and all foreign countries which may be granted therefor and thereon, and reissues, reexaminations and extensions of said Letters Patent, and any rights under the International Convention for the Protection of Industrial Property, same to be held and enjoyed by Assignee, for its own use and benefit and the use and benefit of its successors, legal representatives and assigns, to the full end of the term or terms for which Letters Patent may be granted and/or extended, as fully and entirely as the same would have been held and enjoyed by Assignor, had this sale and assignment not been made;

AND Assignor requests the Commissioner of Patents and Trademarks to issue Letters Patent of the United States to Assignee, as Assignee of the inventions and the Letters Patent to be issued thereon, for the sole use and benefit of Assignee, its successors, legal representatives and assigns;

PATENT REEL: 027110 FRAME: 0534 AND Assignor hereby grants the following individuals the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document: All practitioners at Customer Number 30423.

STMicroelectronics Asia Pacific Pte Ltd.

Date: October 4, 2011

Signature:

Attorney-in-Fact

(09-TPY-171/851663.501) 501 Assignment - ST Assi Pac to ST PTE LTD..DOC